

ABSTRACT OF THE DISCLOSURE

A semiconductor device having grooves uniformly filled with semiconductor fillers is provided. Both ends of each of narrow active grooves are connected to an inner

5 circumferential groove surrounding the active grooves. The growth speed of semiconductor fillers on both ends of the active grooves becomes equal to that at their central portions.

As a result, a semiconductor device having the active grooves filled with the semiconductor fillers at a uniform height is

10 obtained.